

## **REMARKS/ARGUMENTS**

Applicants' attorneys appreciate the Examiner's thorough search and examination of the present patent application.

Claims 4, 5, 7 and 14 have been canceled, and claim 1 has been amended to define applicants' invention. Applicants respectfully submit that the changes to the claims make explicit that which applicants believed to be already implicit and are not, therefore, made for statutory purposes related to patentability.

Claims 1-9, 11, 12 and 14 stand rejected under 35 U.S.C. §102 as being anticipated by Wislocky, et al. ("Wislocky", U.S. Patent No. 3,831,067). Further, claims 10 and 13 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Wislocky in combination with Kouchi (JP55-050659). Also, claims 1-12 and 14 stand rejected under 35 U.S.C. §103(a) as being unpatentable over Toyo (JP08-186135) in combination with Wislocky. Applicants respectfully traverse these rejections.

Claim 1, as amended, includes a compression assembled semiconductor package comprising a semiconductor die. Claim 1 further provides an "insulation ring" comprising an "interior wall" having first and second "grooves." Claim 1 further includes "a first rib extending from [a] first pole flange and a second rib extending from [a] second pole flange." Furthermore, claim 1 includes first and second respective "extending projections" from the first and second flanges, each "comprising at least one of a squared tab and a semi-circular distal end." The first extending projection is "forced into [the] first groove", and [the] "second extending projection is forced into said second groove." The die is "held in place between [the] first pole and [the] second pole as a function of compressing [the] first and second extending projections into [the] first and second grooves."

None of the cited references teach or suggest this combination of elements defined in claim 1, either alone or in combination.

Wislocky, for example, is a typical prior art "hockey puck" package, as described in the background section of applicants' patent application. Unlike applicants' claim 1 package, the package taught by Wislocky does not include first and second "extending projections" from respective first and second poles that include first and second "ribs" and respective "squared tabs" and/or "semi-circular distal ends" that are force fitted into respective first and second

grooves in an "annular insulation ring." Instead, two "slots 34 and 35" are taught that have "radial widths toward their bases which are slightly greater than the thickness of flanges 29 and 30" (see column 2, lines 49-61, and Figs. 2 and 3). Since the thickness of slots 34 and 35 is greater than that of flanges 29 and 30, the flanges are "easily inserted" into the slots. An adhesive or cement is, accordingly, required to "secure headers 25 and 26 to the ring 33." Applicants' claim 1, in contrast, does not require adhesive or cement, as the squared tab and/or semi-circular distal ends are forced into respective grooves, as called for by the claims. Unlike Wislocky, applicants' claim 1 semiconductor die is held in place between the poles as a function of compressing the first and second extending projections into the first and second grooves. Thus, applicants' claim 1 is patentably distinct from Wislocky.

Reconsideration is respectfully requested.

Kouchi and Toyo also fail to disclose these features, as defined in claim 1.

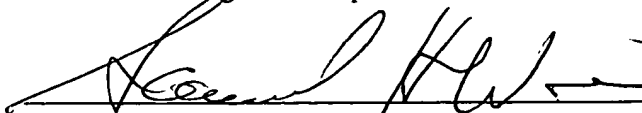
Claims 2-13 depend directly or indirectly from claim 1 and are, therefore, patentable for the same reasons, as well as because of the combination of features in those claims with the features set forth in claim 1. Reconsideration is, therefore, requested.

The application is believed to be in condition for allowance. Such action is earnestly solicited.

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as First Class Mail in an envelope addressed to: Mail Stop Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, Virginia 22313-1450, on June 8, 2005:

Samuel H. Weiner

Name of applicant, assignee or  
Registered Representative

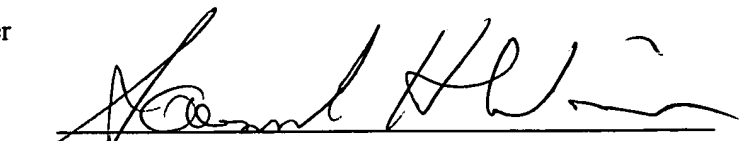
  
Signature

June 8, 2005

Date of Signature

SHW:JJF:ck

Respectfully submitted,



Samuel H. Weiner

Registration No.: 18,510

OSTROLENK, FABER, GERB & SOFFEN, LLP

1180 Avenue of the Americas

New York, New York 10036-8403

Telephone: (212) 382-0700